Electronic Acknowledgement Receipt					
EFS ID:	1250086				
Application Number:	10717122				
Confirmation Number:	7303				
Title of Invention:	Dielectric barrier layer for a copper metallization layer having a varying silicon concentration along its thickness				
First Named Inventor:	Larry Zhao				
Customer Number:	23720				
Filer:	J. Mike Amerson/Mary Paul				
Filer Authorized By:	J. Mike Amerson				
Attorney Docket Number:	2000.106900				
Receipt Date:	12-OCT-2006				
Filing Date:	19-NOV-2003				
Time Stamp:	16:20:45				
Application Type:	Utility				
International Application Number:					

# Payment information:

Submitted with Payment no	Submitted with Payment	no
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## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		Response_to_Office_Action_ Dated_7_12_06.pdf	98468	yes	6

	Multipart Description			
	Doc Desc	Start	End	
	Amendment - After Non-Final Rejection	1	1	
	Applicant Arguments/Remarks Made in an Amendment	2	6	
Warnings:		-		

Information:

Total Files Size (in bytes): 98468

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### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

## National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.